CLEAN VERSION

IN THE ABSTRACT

Please delete the Abstract that was filed on November 6, 2001 and replace with the following paragraph.

A1

A method of laser marking metals, plastics, ceramic materials, glazes, glass ceramics, and glasses of any desired form, which includes applying to the material to be marked a variable thickness layer of marking material containing energy absorbing enhancers then irradiating said layer with a laser or diode based energy source such that the radiation is directed onto said layer in accordance with the form of the marking to be applied, and using a laser or diode based energy source of a wavelength which is sufficiently absorbed by the marking material so as to create a bonding of the marking material to the surface of the workpiece at the irradiated areas.

IN THE SPECIFICATION

Please delete the first paragraph under the heading CROSS RELATED PATENTS in the Specification that was filed on November 6, 2001 and replace with the following paragraph.

A2

This application is a divisional application from U.S. Application Ser. No. 09/477,921 filed January 5, 2000, issued as U.S. Pat. No. 6,313,436 on November 6, 2001, which was a divisional of the parent U.S. Application Ser. No. 08/925,031 filed September 8, 1997 and issued as U.S. Pat. No. 6,075,223 on June 13, 2000.